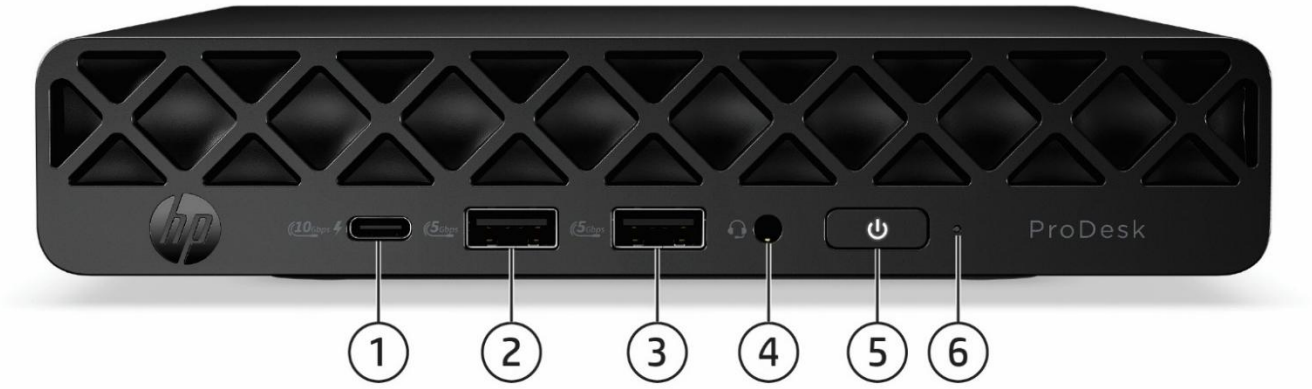
Overview

HP ProDesk 2 Mini G2i Desktop PC



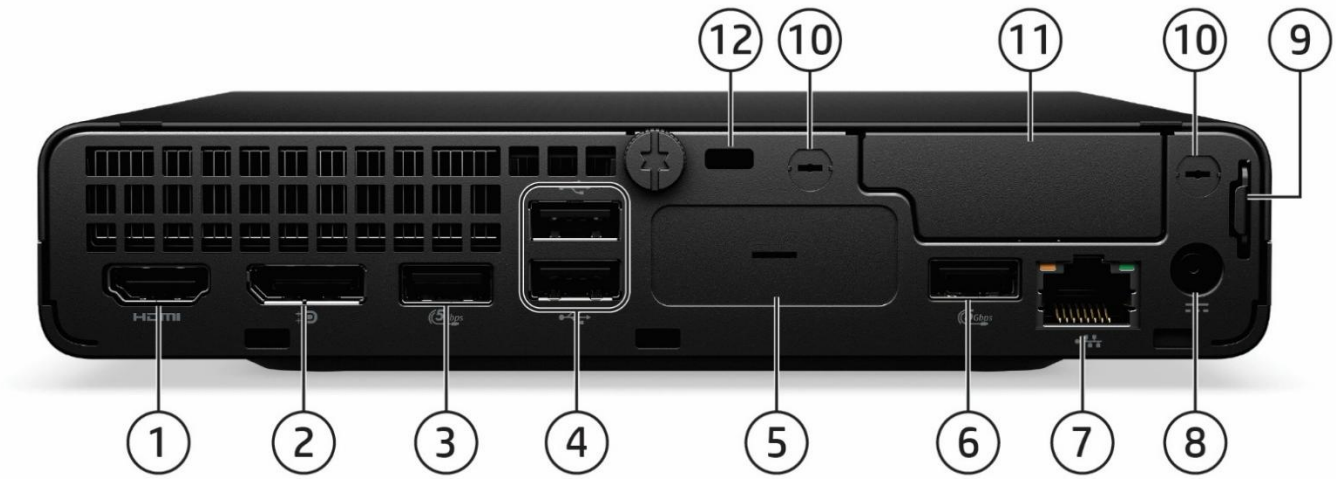
1. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-A SuperSpeed USB 5Gbps signaling rate port
3. Type-A SuperSpeed USB 5Gbps signaling rate port
4. Combo Audio Jack with CTIA and OMTP headset support
5. Dual-state power button
6. SSD activity light

Not shown

(2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280 socket for storage)

Overview

HP ProDesk 2 Mini G2i Desktop PC



1. HDMI 2.1 TMDS 6Gbps
2. DisplayPort™ 2.1 HBR3
3. Type-A SuperSpeed USB 5Gbps signaling rate port
4. Type-A Hi-Speed USB 480Mbs signaling rate port (2)
5. Flex Port 1[1], choice of:
   - HDMI 2.1 FRL 12 Gbps
   - DisplayPort 2.1 UHBR20
   - USB-C (10Gbps) w/ 100W power intake
   - Dual Type A SuperSpeed USB 5Gbps signalling rate port
   - VGA
   - Serial
6. Type-A SuperSpeed USB 5Gbps signaling rate port
7. RJ45 Network connector
8. Power connector
9. Retractable Padlock loop
10. External WLAN antenna opening
11. Flex Port 2[1], choice of:
    - Serial
    - Dual Type A SuperSpeed USB 5Gbps signalling rate port
12. Standard cable lock slot (10 mm)

1. Must be configured at time of purchase

AT A GLANCE

- Intel® Core™ processor (up to Core™ 7) featuring integrated Intel® UHD Graphics
- Choice of Windows 11 Professional, Windows 11 Home, and FreeDOS Up to 64GB of DDR5 Synchronous Dynamic Random Access Memory (SDRAM).
- Support for up to three monitors via native HDMI 2.1 TMDS 6Gbps, native DisplayPort™ and optional video output flex module.
- Optional Wi-Fi 6E and Wi-Fi 6 connectivity.
- Trusted Platform Module (TPM) 2.0.
- VESA mounting incorporated into chassis design in the bottom case.
- Dust filter and Port cover available, External Antenna Ports preserved on chassis.
- High efficiency energy saving power supply with both AC barrel type and AC Type-C adapters.
- PC chassis and all internal components and modules are manufactured with low halogen content.
- Protected by HP Services, including limited warranties up to 1-1-1(terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support.
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 / UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B) v.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled

FreeDOS
Windows 11 Pro[1]
Windows 11 Pro Education[1]
Windows 11 Home - HP recommends Windows 11 Pro for business[1]
Windows 11 Home Single Language - HP recommends Windows 11 Pro for business[1]
Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume Licensing Agreement)[1,2]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS

Intel® Core™ Processors

Intel® Core™ 3 304 Processors 15W Base power, 35W Turbo power Up to 4.3 GHz max Turbo frequency with Intel® Turbo Boost Technology[2] 6MB cache, 5 cores and threads, 15 NPU TOPs, Intel® 1Xe Graphics

Intel® Core™ 5 315 Processors 15W Base power, 35W Turbo power Up to 4.4 GHz max Turbo frequency with Intel® Turbo Boost Technology[2] 6MB cache, 6 cores and threads, 15 NPU TOPs, Intel® 2Xe Graphics

Intel® Core™ 5 320 Processors 15W Base power, 35W Turbo power Up to 4.6 GHz max Turbo frequency with Intel® Turbo Boost Technology[2] 6MB cache, 6 cores and threads, 16 NPU TOPs, Intel® 2Xe Graphics

Intel® Core™ 7 350 Processors 15W Base power, 35W Turbo power Up to 4.8 GHz max Turbo frequency with Intel® Turbo Boost Technology[2] 6MB cache, 6 cores and threads, 17 NPU TOPs, Intel® 2Xe Graphics ® Technology[2]

1. Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
3. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

GRAPHICS

Integrated

Intel® Graphics

NOTE: Intel® integrated Graphics varies by processor.

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

M.2 PCIe NVMe Solid State Drives (SSD)

256GB* M.2 2280 PCIe NVMe SSD
512GB* M.2 2280 PCIe NVMe SSD
1TB* M.2 2280 PCIe NVMe SSD
2TB* M.2 2280 PCIe NVMe SSD
256GB* M.2 2280 PCIe NVMe Self Encrypted OPAL2 SSD**
512GB* M.2 2280 PCIe NVMe Self Encrypted OPAL2 SSD**

***NOTE:** For solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.
****NOTE**: Storage DriveLock does not work with Self Encrypting or Optane based storage.

MEMORY

Type

DDR5-5600(Transfer rates up to 5600MT/s)

Maximum

32GB capacity

Memory Configurations

1 SODIMM
8GB (8GB x 1)
12GB (12GB X 1)
16GB (16GB x 1)
24GB (24GB X 1)
32GB (32GB x 1)

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.
NOTE: Memory modules support data transfer rates up to 5600 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.
NOTE: Memory slots are customer accessible / upgradeable, however, SKUs with LPDDR memory would not be able to access / upgrade as LPDDR memory were soldered onboard.

NETWORKING/COMMUNICATIONS

Networking

Intel® I219-V Gigabit Network Connection LOM (Non-vPro)

Wireless

MediaTek RZ616 Wi-Fi 6E with Bluetooth® 5.3 Wireless Card (802.11ax 2x2[1,2,3]

Realtek RTL8852BE-VT Wi-Fi with Bluetooth® 5.4 Wireless Card (802.11ax 2x2)[3]

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
2. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately.
3. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

NOTE: WiFi-6E might restrict by local regulation.HP will enable countries in the future by upgrading BIOS in default.

KEYBOARDS/POINTING DEVICES

Keyboard and Mouse Combo

HP 275 Wireless Keyboard and Mouse Combo

Keyboard

HP 175 Wired Keyboard

HP 175 AntiMicobial Wired Keyboard[1] (China Only)

HP 375 Secure Smartcard USB Keyboard

Mouse

HP 175 Wired Mouse

HP 175 Antimicrobial Wired Mouse[1] (China Only)

NOTE: Availability may vary by country

SECURITY

TPM 2.0[1] endpoint security controller (Infineon SLB9672). Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.

Intrusion Sensor (integrated in the system board, can be enabled/disabled through BIOS)

Support for chassis cable lock devices

Support for chassis padlocks devices

Serial, USB enable/disable (via BIOS)

Removable media write/boot control

Power-on password (via BIOS)

Setup password (via BIOS)

1. In some scenarios, machines pre-configured with Windows OS might ship with TPM turned off

PORTS

Internal slots and Ports

(1) M.2 PCIe x1 2230 (for WLAN)

(1) M.2 PCIe x4 2280 (for storage)

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket.

Standard User Accessible Ports

Front

(1) Type-C® SuperSpeed USB 10Gbps signaling rate port

(2) Type-A SuperSpeed USB 5Gbps signaling rate port

(1) Combo Audio Jack with CTIA and OMTP headset support

Rear

(2) Type-A SuperSpeed USB 5Gbps signaling rate port

(2) Type-A Hi-Speed USB 480Mbps signaling rate port

(1) Display Port 2.1 HBR3

(1) HDMI 2.1 TMDS 6 Gbps

(1) RJ45

(1)

Configurable Non-PCIe/PCI Slot User Accessible Ports

Rear

Flexible Port#1, choice of USB-C (10Gbps) w/ 100W power intake or DisplayPort 2.1 UHBR20 or HDMI 2.1 FRL 12 Gbps or VGA or 2x USB-A (5Gbps) or Serial port.

Flexible Port#2, choose of Serial (RS-232), Dual USB-A port.

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Buy Microsoft Office (Sold Separately)[1]
HP Desktop Support Utilities
HP app[2]
HP Notifications
HP Support Assistant[3]

Manageability Features
HP Cloud Recovery

Client Security Software
McAfee LiveSafe™ (1 year subscription)[5]

BIOS
Administrator Password
Self-Recovery
Hard Drive Utilities
HP Secure Erase Feature
Secure Boot
Cover Removal Senor
UEFI Self Certification Level: 2.9

1. Microsoft 365 sold separately and requires Internet access for activation.
2. HP app with Multicamera support for Mini Desktop PC will only available on 13th processor and beyond.
2 HP Support Assistant is available on Windows. For more information, please visit: http://www.support.hp.com/help/hp-support-assistant
3. 4. Sold separately and requires Internet access for activation.
5. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail, please refer to: https://support.hp.com/us-en/document/c05115630.
5 Availability may vary by country. McAfee LiveSafe 30-day free trial offer (Internet access required. First 30 days included. Subscription required for live updates afterwards.)

UNIT ENVIRONMENT AND OPERATING CONDITIONS

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT registered where applicable. Based on US EPEAT registration according to EPEAT criteria and EPEAT Climate+ achieved, status and tier level varies by country. Visit http://www.epeat.net for more information.
Low halogen (chassis, all internal components and modules)[1]
TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating:	50° to 95° F (10° to 35° C)[2]
	Non-operating:	-22° to 140° F(-30° to 60° C)
Relative Humidity	Operating:	10% to 90% (non-condensing at ambient)
	Non-operating:	0% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating:	10,000 ft (3048 m)
	Non-operating:	30,000 ft (9144 m)

2. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT Gold registered and EPEAT Climate+ attained in the United States. See http://www.epeat.net for registration status in your country.* • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3) **NOTE***: Based on US EPEAT registration according to EPEAT criteria and EPEAT Climate+, status and tier level varies by country. Visit http://www.epeat.net for more information.
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	2.90 W	2.98 W	2.82 W
Sleep	1.63 W	1.66 W	1.61 W
Off	0.40 W	0.41 W	0.39 W

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	9.9 BTU/hr	10.2 BTU/hr	9.6 BTU/hr
Sleep	5.5 BTU/hr	5.6 BTU/hr	5.5 BTU/hr
Off	1.3 BTU/hr	1.4 BTU/hr	1.3 BTU/hr

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	2.6	16
Fixed Disk – Random writes	2.6	16

Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 2 SODIMM memory slots • Interchangeable M.2 PCIe NVME SSD & 2.5" SATA HDD Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is registered as EPEAT Gold and has attained EPEAT Climate+ in the US, status and tier level varies by country, see http://www.epeat.net. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	450 g
		PAPER/Molded Pulp	74 g
	Internal:	PLASTIC/Polyethylene low density - LDPE	5 g
	The plastic packaging material contains at least 30% recycled content.		
	The corrugated paper packaging materials contains at least 35% recycled content.		
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty[1]: Three-year (3-3-3) or one-year (1-1-1) limited warranty delivers three years or one year of on-site, next business day[2] service for parts and labor and includes free support 24 x 7[3]. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[4]

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

GRAPHICS

Intel® UHD Graphics (integrated)[1]

Graphics Controller	Integrated
HDMI	Supports HDMI 2.1 (TMDS 6Gpbs) Supports HDCP 2.3 Supports audio over HDMI
DisplayPort	Supports DisplayPort 2.1 (up to HBR3) VESA DSC 1.2b
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Graphics/Video API Support	HEVC/H265 442,444 -8b/10b VP9 420/8b,444/8b,420/10b,444/10b HDR DX12 Direct3D11/Direct3D12 API
Max. Resolution (DP)	4096 x 2304@60Hz
Max. Resolution (HDMI)	4096 x 2160 @ 30Hz
Max. Resolution (option VGA)	2048x1536@60Hz
Max Resolution (option DP)	4096 x 2304@60Hz
Max Resolution (option HDMI)	4096 x 2160 @ 30Hz
Max Resolution (Option USB-C, DP Alt mode)	4096 x 2304@60Hz

STORAGE

NOTE: Starting from November 1ST, 2023, all shipments will require Windows to be installed on SSD to provide users a better experience. HDD can only be configured as additional data drives and not the boot drive.

256GB M.2 2280 PCIe NVMe SSD

Capacity	256GB
Interface	PCIe NVMe Gen4x4
Minimum Sequential Read	3200MB/s ±10%
Minimum Sequential Write	1200 MB/s ±20%
Logical Blocks	500,118,192
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Capacity	512GB
Interface	PCIe NVMe Gen4x4
Minimum Sequential Read	3500 MB/s ±20%
Minimum Sequential Write	1600 MB/s ±20%
Logical Blocks	1,000,215,216
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe SSD

Capacity	1TB
Interface	PCIe NVMe Gen4x4
Minimum Sequential Read	3500 MB/s ±20%
Minimum Sequential Write	2700 MB/s ±20%
Logical Blocks	2,000,409,264
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512 GB PCIe Gen5 NVMe™ Value 2280 Solid State Drive

Capacity	512GB
Interface	PCIE Gen5x4
Minimum Sequential Read	9000 MB/s ±20% (in PCIe 5x4 slot)
Minimum Sequential Write	6000 MB/s ±20% (in PCIe 5x4 slot)
Logical Blocks	1,000,215,216
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1 TB PCIe® Gen5x4 NVMe™ Self Encrypted OPAL2 SSD

Capacity	1TB
Interface	PCIE Gen5
Minimum Sequential Read	13000 MB/s ±20% (in PCIe 5x4 slot)
Minimum Sequential Write	9000 MB/s ±20% (in PCIe 5x4 slot)
Logical Blocks	2,000,409,264
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB PCIe Gen5 2280 NVMe Value Solid State Drive

Capacity	2TB
Interface	PCIE Gen5
Minimum Sequential Read	10000 MB/s ±20% (in PCIe 5x4 slot)
Minimum Sequential Write	8000 MB/s ±20% (in PCIe 5x4 slot)
Logical Blocks	4,000,797,360
Features	TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB PCIe Gen3 2280 NVMe Value Solid State Drive

Capacity	256GB
Interface	PCIe NVMe
Minimum Sequential Read	300MB/s ±10%
Minimum Sequential Write	1200 MB/s ±20%
Logical Blocks	500,118,192
Features	TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 SSD

Capacity	256GB
Interface	PCIE Gen4x4
Minimum Sequential Read	3100 MB/s ±20%
Minimum Sequential Write	1200 MB/s ±20%
Logical Blocks	500,118,192
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

512GB PCIe Gen5 2280 NVMe Self Encrypted OPAL2 SSD	
Capacity	512GB
Interface	PCIE Gen 5
Minimum Sequential Read	9000 MB/s ±20% (in PCIe 5x4 slot)
Minimum Sequential Write	6000 MB/s ±20% (in PCIe 5x4 slot)
Logical Blocks	1,000,215,216
Features	TRIM; L1.2; TCG Opal 2.0

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

NETWORKING AND COMMUNICATIONS

Intel® I219v 1 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode only) Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® non vPro™ support with appropriate Intel® chipset components

MediaTek RZ616 Wi-Fi 6E + Bluetooth® 5.3 (802.11ax 2x2, AMD AIM-T)[1,2]	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11j IEEE 802.11k IEEE 802.11mc IEEE 802.11r IEEE 802.11v IEEE 802.11w
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz • 5.925 – 7.125 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 (personal) certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[3]	2.4GHz (MIMO, typical): • 802.11b: +18dBm • 802.11g: +16.5dBm • 802.11n/ac/ax (HT20/VHT20/HE20): +16dBm • 802.11n/ac/ax (HT40/VHT40/HE40): +12.5dBm

Output Power[3]	5GHz (MIMO, typical): • 802.11a: +13dBm • 802.11n/ac/ax (HT20/VHT20/HE20): +13.5dBm • 802.11n/ac/ax (HT40/VHT40/HE40): +12.5dBm • 802.11ac/ax (VHT80/HE80): +11.5dBm • 802.11ax HE160: +11.5dBm 6GHz LPI mode (MIMO, typical): • 802.11a: 0dBm • 802.11ax HE20: +1dBm • 802.11ax HE40: +4dBm • 802.11ax HE80: +7dBm • 802.11ax HE160: +7.5dBm
Power Consumption	• Transmit mode:2.5 W • Receive mode:2 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode:50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[3]	2.4GHz (SISO): •802.11b, 11Mbps: -82dBm maximum • 802.11g, 54Mbps: -71dBm maximum • 802.11n, MCS7: -64dBm maximum • 802.11ac, MCS9: -52dBm maximum •802.11ax, MCS11(HT40): -49dBm maximum 5GHz (SISO): • 802.11a, 54Mbps: -71dBm maximum • 802.11n, MCS07: -64dBm maximum • 802.11ac, MCS9: -52dBm maximum •802.11ax, MCS11(HE80/HE160): -46dBm maximum 6GHz (SISO): • 802.11a, 54Mbps: -71dBm maximum • 802.11n, MCS7: -64dBm maximum • 802.11ac, MCS9: -52dBm maximum •802.11ax, MCS11(HE160): -46dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5/6 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	1. Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 60% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	N/A

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class 1.5 Bluetooth device with a maximum transmit power of + 14 dBm and 10 dBm for BR and EDR, respectively.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.407 ETS 300 328 Low Voltage Directive CE Mark
Bluetooth® Profiles Supported	Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Windows BT profiles support Bluetooth 5.3 Periodic Advertisement interval Encryption key size control enhancements

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
2. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852BE-VT 802.11ax 2x2 Wi-Fi + BLuetooth® 5.4 (802.11ax 2x2, supporting gigabit data rate)[1]	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11j IEEE 802.11k IEEE 802.11mc IEEE 802.11r IEEE 802.11v IEEE 802.11w
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac: max 866.7Mbps • 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum, OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[2]	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 (personal) certification • IEEE 802.11i • WAPI (by request) • EAP

Technical Specifications – Networking

Network Architecture **Models**	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[3]	802.11b: +20dBm 802.11g: +18dBm 802.11a: +18dBm 802.11n HT20(2.4GHz): +17dBm 802.11n HT40(2.4GHz): +17dBm 802.11n HT20(5GHz): +17dBm 802.11n HT40(5GHz): +17dBm 802.11ac VHT80(5GHz): +15dBm 802.11ax HE40(2.4GHz): +13dBm 802.11ax HE80(5GHz): +13dBm
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[2]	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity. Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C) Storage Temperature (–55° to 125° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3/5.4 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class I Bluetooth device with a maximum transmit power of +15.5 dBm for BR and +13dBm for EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C/E, Section 15.247, 15.249 ETSI 300 328, ETSI 301 893
Bluetooth Profiles Supported	Bluetooth 4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan Bluetooth 4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Bluetooth 5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range Windows BT profiles support Bluetooth 5.3 Compliance to the latest errata spetion 12.3 of Bluetooth 5.3 specification ESR 9/10 compliance Host to controller Encryption key control enhancements

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.2. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

INPUT/OUTPUT DEVICES

HP 175 wired Mouse		
Dimensions (LxWxH)	123x65x39 (mm); 4.84x2.56x1.54 (in)	
Weight	80 (g);0.18 (lb)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Electrical	Operating voltage	4.75~5.25V
	Power consumption (typical)	100mA
	Resolution	1,200 DPI
	Sensor	Optical USB mouse sensor
	System Interface	USB
	Cable length	6 ft (1.8 M)
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC

HP 175K Wired Keyboard		
Physical Characteristics	Keys	110keys (US);111(UK);113(JP, BR)
	Dimensions (LxWxH)	428.83 x 117.37 x 19.1 (mm);16.88 × 4.62 × 0.75 (in)
	Weight	435 (g);0.96 (lb)
Electrical	Operating voltage	4.75~5.25V
	Power consumption	100mA
	System Interface	USB
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	Cable length	6 ft (1.8 M)
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Key Structure (Switch type and feeling) (Plunger)	Plunger, Key travel: 2.5mm +/-0.2mm at 120gf, low profile key travel
	Key actuation	60±8g nominal peak force with tactile feedback
	Key life	10 million keystrokes (Life tester)
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC, BIS	

Technical Specifications – Input/Output

HP 175M Antimicrobial Wired Mouse		
Dimensions (LxWxH)	123 x 65 x 39 (mm); 4.84 x 2.56 x 1.54 (in)	
Weight	80 (g);0.18 (lb)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Electrical	Operating voltage	4.75~5.25V
	Power consumption (typical)	100mA
	Resolution	1,200 DPI
	Sensor	Optical USB mouse sensor
	System Interface	USB
	Cable length	6 ft (1.8 M)
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC

HP 175K Antimicrobial Wired Keyboard		
Physical Characteristics	Keys	110 keys (US); 111(UK); 113(JP, BR)
	Dimensions (LxWxH)	428.83 x 117.37 x 19.1 (mm); 16.88 x 4.62 x 0.75 (in)
	Weight	435 (g);0.96 (lb)
Electrical	Operating voltage	4.75~5.25V
	Power consumption	100mA
	System Interface	USB
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	Cable length	6 ft (1.8 M)
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Key Structure (Switch type and feeling) (Plunger)	Plunger, Key travel: 2.5mm +/-0.2mm at 120gf, low profile key travel
	Key actuation	60±8g nominal peak force with tactile feedback
	Key life	10 million keystrokes (Life tester)
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC, BIS	

HP 275 wireless Keyboard		
Physical Characteristics	Keys	107keys (US); 108keys (UK); 110 keys (JP, BR)
	Dimensions (LxWxH)	428.83 x 117.37 x 19.1 (mm);16.88 x 4.62 x 0.75 (in)
	Weight	416 (g); 0.92 (lb)
Electrical	Operating voltage	2.2V~3.3V (BATTERY)
	Power consumption	30mA
	System Interface	2.4GHz Wireless
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Key Structure (Switch type and feeling) (Plunger)	Plunger, Key travel: 2.5mm +/-0.2mm at 120gf, low profile key travel
	Key actuation	60±8g nominal peak force with tactile feedback
	Key life	10 million keystrokes (Life tester)
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Approvals	CB; FCC; IC; UL; ENCOM; ANATEL; SUBTEL; RCM; WPC; BIS; CONATEL; TRA; CE; TUV GS; ICASA; SRRC; DJID; TELEC; VCCI; KCC; SIRIM; NTC; IMDA; NCC; BSMI; NBTC	

HP 275 wireless Mouse		
Dimensions (LxWxH)	123x65x39 (mm); 4.84x2.56x1.54 (in)	
Weight	73 (g); 0.161 (lb) (no Battery)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-32° to 140° F (-40° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Drop (out of box)	6 faces, 76cm, rigid surface
	Drop (in box)	6 faces, 1 corner and 3 edges on rigid surface, drop Height: 91cm
Electrical	Operating voltage	1.5VDC
	Power consumption (typical)	30mA
	Resolution	1,200 DPI
	Sensor	Optical mouse sensor
	System Interface	2.4GHz Wireless
	Cable length	NA
Regulatory approvals	CB; FCC; IC; UL; ENCOM; ANATEL; SUBTEL; RCM; WPC; CONATEL; TRA; CE; TUV GS; ICASA; SRRC; DJID; TELEC; VCCI; KCC; SIRIM; NTC; IMDA; NCC; BSMI; NBTC	

HP USB Business Slim Wired SmartCard CCID Keyboard		
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78 in (440.6 x 144.5 x 1.98 cm)
	Weight	1.32 lb (598g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	100mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CE Marking, TUV, EAC, FCC, cULus/ CSAus, ICES, RCM, VCCI, KCC, BSMI	
Ergonomic compliance	ISO 9241-4, TUVGS	

AUDIO/MULTIMEDIA

Type	Integrated
HD Stereo Codec	Realtek ALC3252
Audio I/O Ports	Front: Headset connector supports a CTIA and OMTP style headset and is retaskable as a Line-in, Line-out, Microphone-in or Headphone-out port
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally
Multi-streaming Capable	Playback multi-streaming allows independent audio streams to be sent to/from the front jacks and integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

POWER SUPPLY

Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current with Energy Efficient* Power Supply	65W≦ 1.6A Average efficiency 88% at 115V Average efficiency 89% at 230V
DC Output	+19.5V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power cord length	3.28 ft. (1.0 m) / 5.9 ft (1.8m)
Dimensions	90 x 51 x 28.5mm
Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current with Energy Efficient* Power Supply	65W≦ 1.6A
DC Output	+20.0 V
Current Leakage (NFPA 99: 2102)	Less than 40 microamps of leakage current at 250Vac/50 Hz with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use.
Power cord length	Duck head
Dimensions	65x 32x 32mm

WEIGHT AND DIMENSIONS[1]

System

Dimensions	6.97 x 7.13 x 1.35 in 177 x 181 x 34.2 mm
Weight[2]	2.07~2.2 lbs 0.94~1.0 kg
Volume	64.4 cu in 1.09 L

Packaging dimensions and weight

Dimensions	**Config-1:** 19.57 x 5.04 x 8.78 in 497 x 128 x 223 mm **Config-2:** 19.61 x 9.25 x 5.20 in 498 x 235 x 132 mm
Weight	7.36 lbs 3.34 kg **MPP/EPE:** 6.4 lbs 2.9 kg

Palletization and Container

Pallet Profile	**Config-1:** 1 unit/carton 18 cartons/layer 5~6 layers per pallet max depending on details of air freight 90~108 units per pallet depending on details of air freight **Config-2:** 1 unit/carton 10 cartons/layer 10~19 layers per pallet max depending on details of ground/sea freight 100~190 units per pallet depending on details of ground/sea freight
Pallet Size Loaded	45.354 x 39.13 x 57.80 in 1152 x 994 x 1468 mm **MPP/EPE:** 46.26 x 39.21 x 103.74 in 1175 x 996 x 2635 mm

1. Packaging material used will vary by country.

After-Market Options (availability may vary by region)

AFTER MARKET OPTIONS

Graphics Solutions	Part Number
HP HDMI Standard Cable Kit	T6F94AA
HP DisplayPort™ To HDMI True 4k Adapter	2JA63AA
HP DisplayPort™ Cable Kit	VN567AA
HP DisplayPort™ To VGA Adapter	F7W97AA
HP DisplayPort™ To DVI-D Adapter	F7W96AA
HP USB to Serial Adapter	J7B60AA
HP HDMI to VGA Adapter	H4F02AA

Desktop Mini Accessories	Part Number
HP Desktop Mini DVD-Writer ODD Expansion Module	K9Q83AA
HP Desktop Mini v4+ VESA Sleeve	99T54AA
HP Desktop Mini v4+ VESA Sleeve with Power Supply Holder	99T55AA
HP B300 PC Mounting Bracket with Power Supply Holder	7DB37AA
HP Desktop Mini Vertical Chassis Stand	G1K23AA

Data Storage Drives	Part Number
HP 512GB 2280 PCIe NVMe Value Solid State Drive	A94C2AA
HP 1TB PCIe-4x4 NVMe Value M.2 Solid State Drive	A94C3AA

Input Devices	Part Number
HP 125 G2 Wired Keyboard	AY2Y7AA
HP 125 Wired Mouse	265A9UT
HP 128 Laser Wired Mouse	265D9AA
HP Wired Desktop 320M Mouse	9VA80AA
HP 320K G2 Wired Keyboard	9SR37UT
HP Wired Desktop 320MK G2 Mouse and Keyboard Combo	9SR36UT
HP 405 Multi-Device Wired Backlit Keyboard	7N7C1AA
HP 475 Dual-Mode Wireless Keyboard	7N7B9AA
HP 105 Sanitizable Mouse Pad	8X595AA
HP 205 Sanitizable Desk Mat	8X597AA

Memory	Part Number
HP 8GB DDR5-5600 DIMM	A9TF0AA
HP 16GB DDR5-5600 DIMM	A9TF1AA
HP 32GB DDR5-5600 DIMM	A9TF3AA

Multimedia Devices	Part Number
HP S101 Speaker bar	5UU40AA
HP Stereo USB Headset G2	428K6AA

After-Market Options (availability may vary by region)

Security Devices	Part Number
HP Keyed Cable Lock 10mm	T1A62AA
HP Master Keyed Cable Lock 10mm	T1A63AA

Stands and Mounting Accessories	Part Number
HP B560 PC Mounting Bracket	763U8AA
HP B200 PC Mounting Bracket	762T5AA
HP B250 PC Mounting Bracket	8RA46AA
HP B300 PC Mounting Bracket	2DW53AA
HP Quick Release Bracket 2	6KD15AA

Change Log

Date of change:	Version History:		Description of change:
	From v1 to v2		
	From v2 to v3		
	From v3 to v4		
	From v4 to v5		
	From v5 to v6		
	From v6 to v7		